

GBU8005 THRU GBU810

GLASS PASSIVATED BRIDGE RECTIFIER

Reverse Voltage - 50 to 1000 Volts Forward Current - 8.0 Ampere

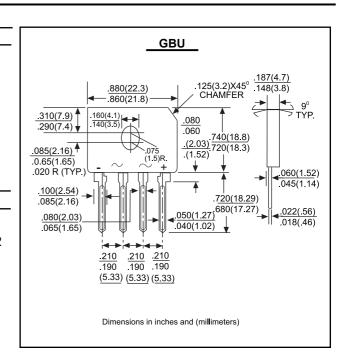
FEATURES

- Glass passivated chip junction
- Reliable low cost construction utilizing molded plastic technique
- Ideal for printed circuit board
- Low reverse leakage current
- Low forward voltage drop
- High surge current capabiliy

MECHANICAL DATA

- Case:Molded plastic, GBU
- Terminals: Terminals: Leads solderable per MIL-STD-202 method 208 guaranteed
- Epoxy: UL 94V-0 rate flame retardant
- Mounting Position: Any





MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbols	GBU 8005	GBU 801	GBU 802	GBU 804	GBU 806	GBU 808	GBU 810	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current with Heatsink at $T_{\rm C}$ = 100 $^{\rm o}$ C	I _(AV)	8.0							Α
Peak Forward Surge Current, 8.3 ms Single Half-Sine -Wave superimposed on rated load (JEDEC Method)	I _{FSM}	200							Α
Maximum Forward Voltage at 4.0 A DC and 25 °C	V _F	1.0							V
Maximum Reverse Current at T _A = 25 °C at Rated DC Blocking Voltage T _A = 125 °C	I _R	5.0 500							μA
Typical Junction Capacitance 1)	CJ	70							pF
Typical Thermal Resistance 2)	$R_{\theta JC}$	2.2							°C/W
Operating and Storage Temperature Range	T_J,T_S	-55 to +150							°C

¹⁾ Measured at 1 MHz and applied reverse voltage of 4 VDC.

²⁾ Thermal resistance from junction to case with device mounted on 300 mm X 300 mm X 1.6 mm Cu plate heatsink.



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RATINGS AND CHARACTERISTIC CURVES

